Abstracts

Micromachined Conformal Packages for Microwave and Millimeter-Wave Applications

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High frequency circuit performance is significantly influenced by its RF package configuration. This paper presents the use of Si micromachining to develop a miniature package that conforms to the circuit geometry while providing physicai and electromagnetic shielding. The advantages of a conformal package, other than reduced size, are control of package resonances, the capability to isolate individual circuit elements and improve circuit performance through elimination of parasitic radiation. In addition, the use of micromachining provides reduced fabrication tolerances and most importantly lower cost.

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